



ON Semiconductor  **Efficient Innovations**

Products Applications Tools About MyON

Home > About > Quality > Environmental Programs > RoHS (Material Composition)

Material Composition

Locate Pb-free (RoHS) and Halogen-free Material content details.

AP1302CSSL005MGA0-DR Download:  Excel





Sort by entry order

Use ~ for the exact search match (i.e. ~NTS2101PT1).

2 Non-hybrid devices found

Non-hybrid devices

1 - 2 of 2 [1]

Base part	Part	Status	H	Y	IPCL753	Mold Compound						Die Attach				Die			Organic Substrate and Solder Mask					Solder Ball				Wire Bond		Conflict Minerals		TOTAL					
						AlHydroxide [%]	Phenolic Resin [%]	Epoxy + Phenol Resin [%]	Carbon black [%]	Fused silica [%]	Silica crystalline [%]	Weight [mg]	Epoxy resins [%]	Fused silica [%]	Acrylic resins [%]	Polyimide [%]	Weight [mg]	Misc. [%]	Si [%]	Al [%]	Weight [mg]	Fiber glass [%]	Organic Resin (Bismaleimide + Triazine + Epoxy resin) [%]	Cu [%]	Ni [%]	Au [%]	Cured Resin of Solder Mask [%]	Weight [mg]	Ag [%]	Sn [%]	Cu [%]		Weight [mg]	Cu [%]	Weight [mg]	Au [1=Yes]	Sn [1=Yes]
						21645-51-2	n/a	n/a	1333-86-4	60676-86-0	14808-60-7	n/a	n/a	60676-86-0	n/a	n/a	7440-21-3	7429-90-5	n/a	65997-17-3	13676-54-5 1156-51-0 29690-82-2 25068-38-6	7440-50-8	7440-02-0	7440-57-5	n/a	n/a	7440-22-4	7440-31-5	7440-50-8	n/a	7440-50-8	n/a	7440-57-5	7440-31-5	n/a		
	AP1302CSSL005MGA0-DR	Active	Y		 	3.00	4.50	6.00	0.30	75.90	10.30	33.8000	7.50	54.50	10.50	27.50	0.8000	0.38	99.63	0.99	8.0200	21.19	13.08	49.36	1.90	0.25	14.22	12.3100	3.00	96.50	0.50	12.5600	100.00	0.6100	1.00000	1.00	68.1000
	AP1302CSSL005MGA0-DR1	Active	Y		 	3.00	4.50	6.00	0.30	75.90	10.30	33.8000	7.50	54.50	10.50	27.50	0.8000	0.38	99.63	0.99	8.0200	21.19	13.08	49.36	1.90	0.25	14.22	12.3100	3.00	96.50	0.50	12.5600	100.00	0.6100	1.00000	1.00	68.1000

1 - 2 of 2 [1]

Materials Disclosure Disclaimer

Note: Even though all possible efforts have been made to provide you with the most accurate information, we can not guarantee to its completeness and accuracy due to the fact that the data has been compiled based on the ranges provided and some information that may not have been provided by the subcontractors and raw material suppliers to protect their business proprietary information.

Based on the above considerations, this information is provided only as estimates of the average weight of these parts and the anticipated significant toxic metals components. These estimates do not include trace levels of dopants and metal materials contained within silicon devices in the finished products.

There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBBE or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products.

For further explanation on material composition calculations, please view our [Product Chemical Content Brochure](#).